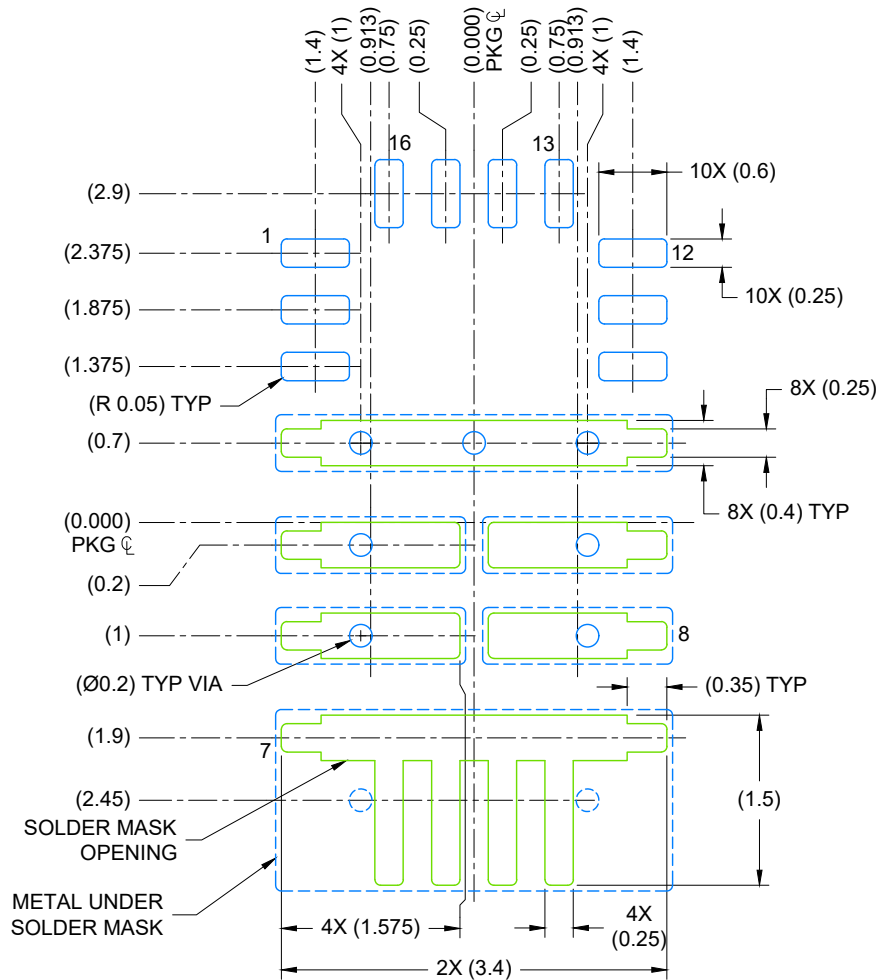
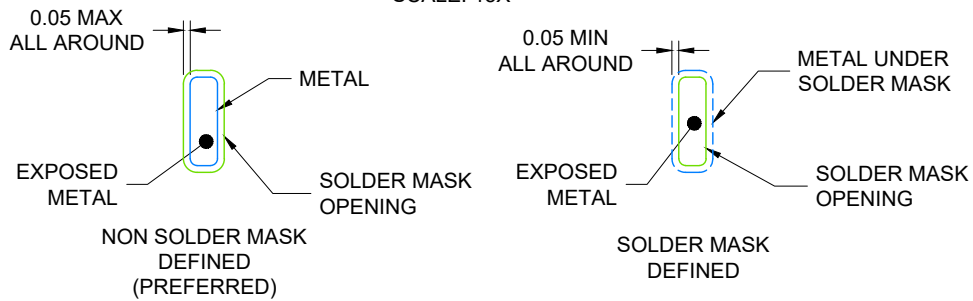


**NOTES:**

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.



**LAND PATTERN EXAMPLE**  
EXPOSED METAL SHOWN  
SCALE: 15X

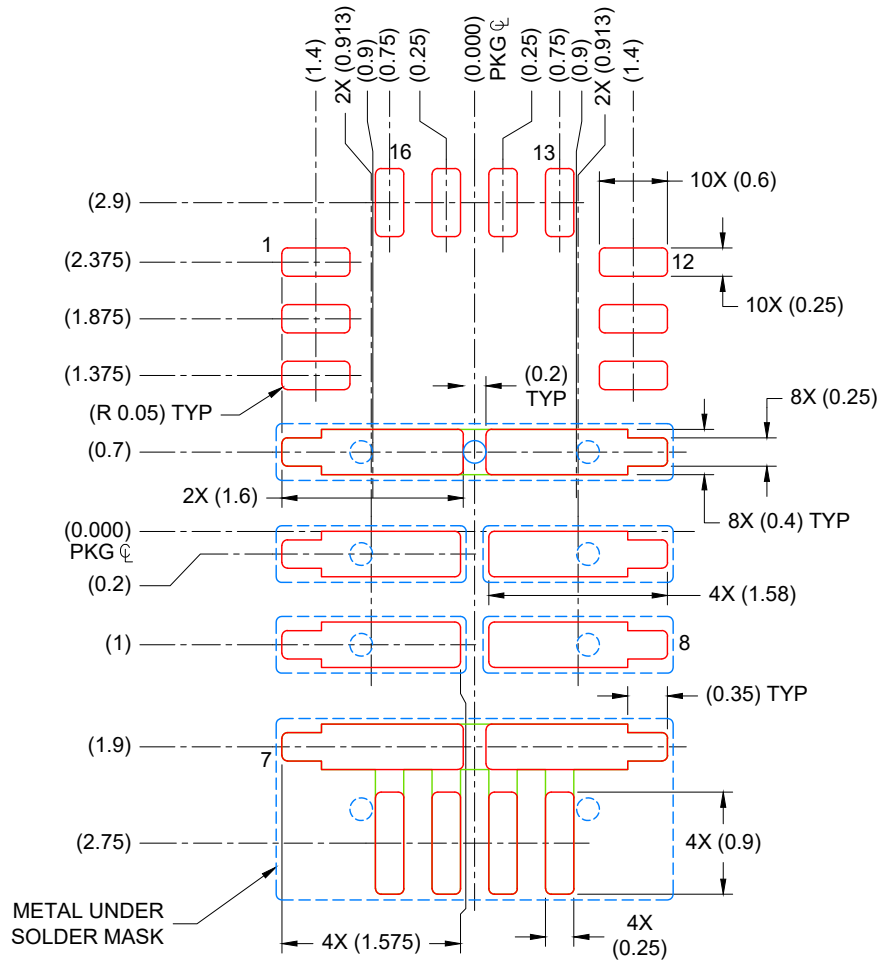


**SOLDER MASK DETAILS**

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NOTES: (continued)

3. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/sluea271](http://www.ti.com/lit/sluea271)).
4. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.



**SOLDER PASTE EXAMPLE**  
 BASED ON 0.1 mm THICK STENCIL  
 SCALE: 15X

PAD 4: 93%; PAD 7: 89%

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NOTES: (continued)

- 6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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